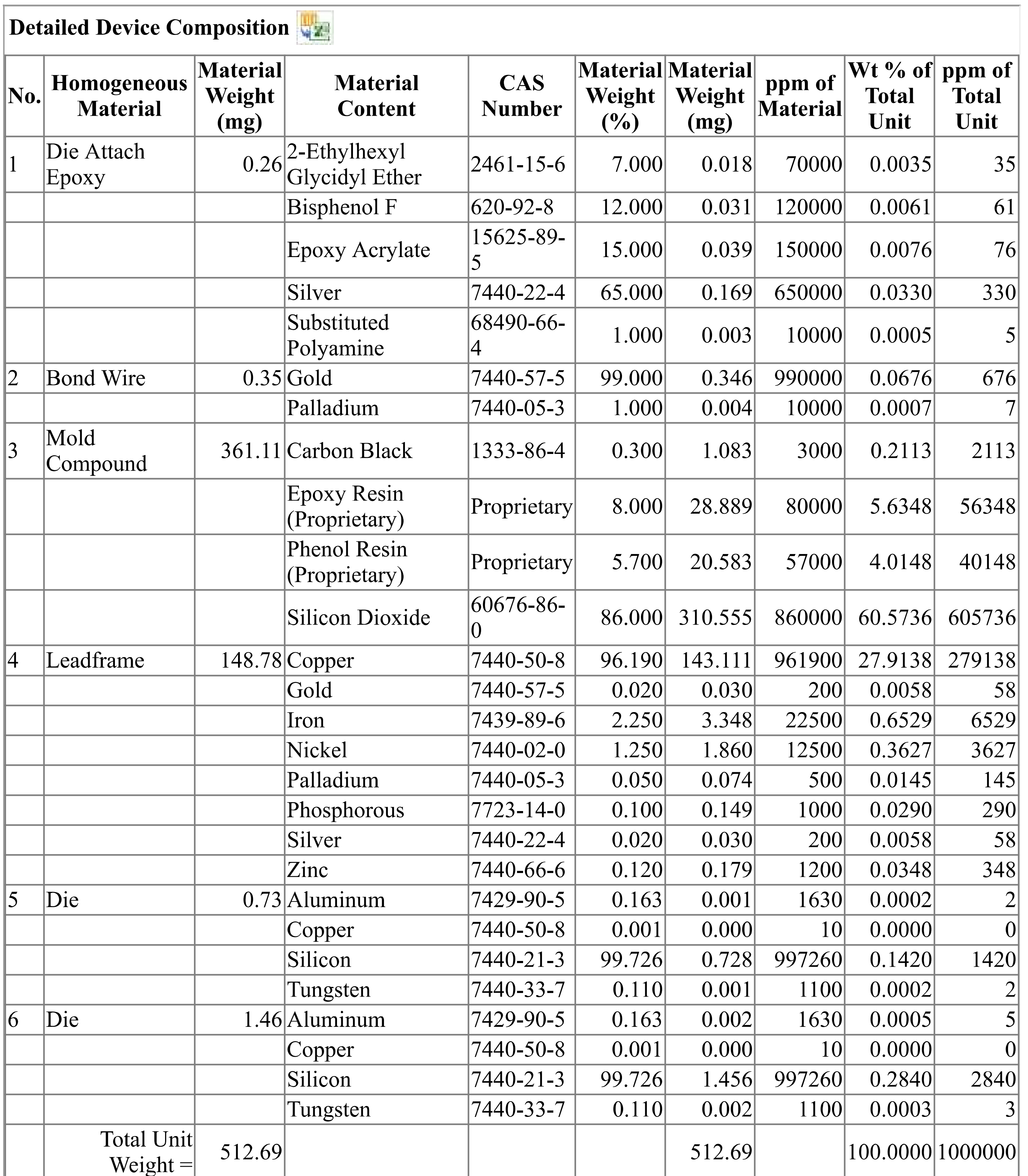
Date: 4/19/2021
Material Number: SI82398BD4-IS
Pkg Config.: PK1043



Detailed Device Composition

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Die Attach Epoxy	0.26	2-Ethylhexyl Glycidyl Ether	2461-15-6	7.000	0.018	70000	0.0035	35
			Bisphenol F	620-92-8	12.000	0.031	120000	0.0061	61
			Epoxy Acrylate	15625-89-5	15.000	0.039	150000	0.0076	76
			Silver	7440-22-4	65.000	0.169	650000	0.0330	330
			Substituted Polyamine	68490-66-4	1.000	0.003	10000	0.0005	5
2	Bond Wire	0.35	Gold	7440-57-5	99.000	0.346	990000	0.0676	676
			Palladium	7440-05-3	1.000	0.004	10000	0.0007	7
3	Mold Compound	361.11	Carbon Black	1333-86-4	0.300	1.083	3000	0.2113	2113
			Epoxy Resin (Proprietary)	Proprietary	8.000	28.889	80000	5.6348	56348
			Phenol Resin (Proprietary)	Proprietary	5.700	20.583	57000	4.0148	40148
			Silicon Dioxide	60676-86-0	86.000	310.555	860000	60.5736	605736
4	Leadframe	148.78	Copper	7440-50-8	96.190	143.111	961900	27.9138	279138
			Gold	7440-57-5	0.020	0.030	200	0.0058	58
			Iron	7439-89-6	2.250	3.348	22500	0.6529	6529
			Nickel	7440-02-0	1.250	1.860	12500	0.3627	3627
			Palladium	7440-05-3	0.050	0.074	500	0.0145	145
			Phosphorous	7723-14-0	0.100	0.149	1000	0.0290	290
			Silver	7440-22-4	0.020	0.030	200	0.0058	58
			Zinc	7440-66-6	0.120	0.179	1200	0.0348	348
5	Die	0.73	Aluminum	7429-90-5	0.163	0.001	1630	0.0002	2
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.728	997260	0.1420	1420
			Tungsten	7440-33-7	0.110	0.001	1100	0.0002	2
6	Die	1.46	Aluminum	7429-90-5	0.163	0.002	1630	0.0005	5
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	1.456	997260	0.2840	2840
			Tungsten	7440-33-7	0.110	0.002	1100	0.0003	3
	Total Unit Weight =	512.69				512.69		100.0000	1000000